

Secure Product Lifecyle

Implementation Attacks on High-Security Devices

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WHEN YOU NEED TO BE SURE

PART I – From Security Target to Testplan

WHITEBOX VS. BLACKBOX TESTING

Blackbox

- Evaluator gets same (public) information as a consumer
- Unknown algorithm details and countermeasures
- Samples same/similar to product
- No further support from developer

GREY BOX

Whitebox

- **Exaluator has in-depth knowledge about internals**
- Algorithms and countermeasures declared and described in detail
- Samples prepared for testing (opened, added functionality)
- Support from developer
- \rightarrow More common in high-security domains

WHITEBOX VS. BLACKBOX TESTING

Scope: Use any measures to break the device

- Social engineering (e.g. phishing)
- Attack the DUT in an uncertified way (e.g. configuration)
- Attack the IT environment of the TOE
- Attack the development or production environment

- Scope: Asset clearly defined and separated
	- User behaviour is defined
	- Environment is defined
	- Configuration is defined
	- Security functionality is defined
	- Development and production environment is defined and certified

WHITEBOX VS. BLACKBOX TESTING

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24. Aug 2010

Chaos Computer Club hacks German ID Card 2.0

SECURITY STANDARDS VULNERABILITY ANALYSIS

- What shall be tested?
	- TOE (Target of evaluation)
	- Secure configuration
	- Test depth
	- *Example: TD Smartcards and Similar Devices*
- How is tested?
	- Tools & procedures depending on TOE, e.g. for TD Smartcards and Similar **Devices**
- When is the device broken?
	- If the white box attack is successful, is the device secure or not?
	- What means secure?
	- E.g.CC defines 'secure' as **TOE is resistant against an attacker with different attack potentials: no rating, basic, enhanced-basic, moderate or high**

EXAMPLE COMMON CRITERIA AVA – DUT

- **Security Target**
	- TOE is defined (Target of Evaluation == Device under Test)
	- **EAL level is defined**
	- Security Target: High level requirements (SFR) and services (SF) of the full security functionality
	- Cryptographic security functionality is additional reflected in the Cryptographic mechanisms subsection / table

Simplified CC mapping between SFRs and AVA test:

TEST PLAN INPUT

Test plan updates while performing AVA testing

TEST PLAN INPUT

Developer must provide design documentation, developer tests, source code etc. depending on the assurance level.

- Test Guidance for security standards
	- For the German scheme, the test guidance is defined by the German certification body (BSI) additionally to CC framework
	- \blacksquare AIS 46
		- ECC
		- RSA, DSA, Diffie-Hellman
		- Memory Encryption
	- AIS 20, AIS 31
		- RNG including
			- DRG Deterministic random number generator
			- PTG True physical random number generator
			- **E** Hybrid random number generator

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TEST PLAN INPUT

Bundesamt für Sicherheit in der Informationstechnik

- Example: Minimum Requirements for Evaluating Side-Channel Attack Resistance of RSA, DSA and Diffie-Hellman Key Exchange Implementations Part of AIS 46 (1)
	- Chapter 2: Side-channel analysis
	- Chapter 3: Modular exponentiation (RSA, DSA,DH) // Chapter 4: RSA etc.

EXAMPLE TOE SNAPDRAGON 855 MOBILE PLATFORM (SOC)

Multigigabit everything

The world's first commercial 5G mobile platform unleashes transformative 5G experiences with the Snapdragon X50 5G modem while harnessing multigigabit 4G connectivity. Combined with a new era of Wi-Fi performance, this is innovation for the next generation.

Powerful, intuitive experiences

Snapdragon 855 is powered by new architecture improvements and leading 7nm process technology, a giant leap in CPU smartphone performance, and a Hexagon processor that's purpose built for Al. This platform packs unimaginable performance and power efficiency for the next echelon of 5G, AI and XR. It delivers powerful, intuitive experiences in the tiniest of packages - all while providing what matters most: insane battery life.

Al to the 4th Power

Our 4th generation on-device AI engine is the ultimate personal assistant for camera, voice, XR and gaming delivering smarter, faster and more secure experiences. Utilizing all cores, it packs 3 times the power of its predecessor - providing stellar on-device AI capabilities.

Cinema-grade videography

From bleeding-edge color to a new evolution of cinemagrade videography, this platform sets brilliant new standards for mobile - including the world's first Computer Vision (CV) ISP delivering 4K HDR video capture with Portrait Mode and world's first to capture HDR10+ video.

Captivating entertainment

Go big, even when you're not at home. The Snapdragon 855 steals the show with 4K HDR video playback, your motion pictures will be brilliant, scene-by-scene and frame-by-frame. 5G makes XR real time, so fully immersive interactions happen at the speed of life. Plus, Snapdragon Elite Gaming equates to multi-player experiences that mimic human reflex. Game on.

Cutting edge connectivity

The Qualcomm[®] FastConnect" 6200 subsystem delivers a new era of wireless connectivity with Wi-Fi 6 innovations for new and enhanced mobile experiences, as well as integrated Bluetooth 5.1 with advanced low latency and audio capabilities.

- Security Target: Qualcomm® Secure Processing Unit SPU230 Core Security Target Lite, 80-NU430-6 Rev. B May 3, 2019
- The target of evaluation (TOE) is the secure processing unit (SPU) subsystem serving as a secure element within a package systemon-chip (SoC).
- The TOE is an independent subsystem that is integrated in a system-on-chip (SoC) in a manner that is agnostic to the hardware and software implementation details. The TOE serves as an independent root of trust within the SoC. It does not rely on any external entity for any security enforcement, allowing it to be evaluated as a separate entity. It has its own ROM code for secure boot operations.

EXAMPLE TOE HARDWARE SEPARATION

<https://www.anandtech.com/show/13663/qualcomm-tech-summit-day-2>

EXAMPLE TOE HARDWARE SEPARATION

https://www.bsi.bund.de/SharedDocs/Zertifikate_CC/CC/System_on_a_Chip_SOC/1045.html

EXAMPLE TOE HARDWARE SEPARATION

SGS

- 3 out of 36 SFRs
	- FCS_COP.1/AES Cryptographic operation AES
		- The TSF shall perform encryption and decryption and authentication when using CCM mode in accordance with a specified cryptographic algorithm AES in ECB mode, CBC mode, CTR mode, CCM mode and cryptographic key sizes 128-, 256-bit that meet the following: Specification for the ADVANCED ENCRYPTION STANDARD (AES) (FIPS PUB 197), Recommendation for Block Cipher Modes of Operation, Methods and Techniques (NIST SP 800-38A), Recommendation for Block Cipher Modes of Operation: The CCM Mode For Authentication and Confidentiality (NIST SP 800-38C).
	- FCS_CKM.4/AES Cryptographic key destruction AES
		- The TSF shall destroy cryptographic keys in accordance with a specified cryptographic key destruction method overwriting with zeros or overwriting the protecting key encryption key in the key hierarchy with zeros that meets the following: none.
	- FPT PHP.3 Resistance to physical attacks
		- The TSF shall resist *physical manipulation and physical probing* to the *TSF* by responding automatically such that the SFRs are always enforced

WHITE BOX TEST PLAN

Assessment

- **EAL.4 augmented by AVA_VAN.5**
- AES, SHA, HASH, RNG
- Side-Channel and fault injection attacks
- Reverse engineering

Out-of-scope

▪ …

- Attacks on any other functionality or with non-certified configuration
- EC cryptographic operations
- No assessment of any feature like 5G, AI or other
- No Pentesting on network interfaces

SUM UP PART I

- Security Features and EAL defined by the developer
- Developer provides white box test interfaces
	- Documentation, Samples, Support
	- Clear scope of testing including detailed rules
		- CB ensures that those are sufficient and up-to-date
- Rating scheme for vulnerabilities defined
	- Flexible for different attack potentials
- Test plan can be detailed a priori to the assessment
- Test plan can be updated a posteriori during the assessment

PART II – From Testplan to Attack Potential

AGENDA

Part 2 – Practical evaluation work

- **EXECT:** Starting from an initial version of the testplan
- **EXECTE:** Step-by-step through a typical analysis flow
- **•** Details on certain aspects
- **EXECUTE:** Attack potential rating

TYPICAL ANALYSIS FLOW

- Implementation Analysis
- 2. Modelling of the Attacked Algorithm
- 3. Identification of Samples
- 4. Preparation of Samples
- 5. Establishing a Communication Channel
- 6. Bypassing Countermeasures
- 7. Target Identification
- 8. Worst Case Analysis
- 9. Attack Paths & Methods
- 10. Attack Rating

1. IMPLEMENTATION ANALYSIS

- Inputs:
	- Security functional requirements (crypto table)
	- Gathered information from document work
		- E.g. HW/SW countermeasures
		- $TSFI \rightarrow$ interfaces
		- Parameters
		- Options (configuration)
	- Implementation representation (source code/design files)
	- **Workshops with developer**
		- Clarify what is not understood well enough
	- **EXEC** Guidelines from Standards, papers, etc.
		- What shall be tested? How shall be tested (rather high-level)?
		- \rightarrow ensure certain quality level, independent of ITSEF lab
	- Inputs from other evaluation steps
	- **Early version of the test plan**

1. IMPLEMENTATION ANALYSIS

Gathered information

- Targeted algorithm and how to trigger it (efficiently)
- **Floor plan (ideally location on chip)**
- **Implementation details of the algorithm**
- **Environmental condition boundaries**
- **EXECUTE:** Available clock frequencies
- **EXECUTE:** Interrupt or polling behavior
- **EXECONFIGURATION OPTIONS**
	- min. security level allowed by guidance
	- max leakage, vulnerability to attacks
	- countermeasures
- etc.

1. IMPLEMENTATION ANALYSIS

Output \rightarrow refined testplan

■ For each function in scope (TSF/TSFI, security claim)...

- **EXT** Ideally divides a complex function into smaller parts (still need to evaluate and rate as a whole)
- **EXECT:** List of tests covering different aspects (attack paths)
- And covering different countermeasures
- **EXT** Ideas and strategies how to test (e.g. functions to call, bypass countermeasrues)

2. MODELLING OF THE ATTACKED ALGORITHM

© Photo recreation by Bryan Beasley

- What you read and understand \neq what is implemented (often not even what is written)
- Idea: To implement something you need a certain level of understanding.
- Goals:
	- Gain enough information to analyze and attack algorithm
	- Make decision what parts are most vulnerable \rightarrow select target, e.g. intermediate
	- Calculate required intermediates (SCA/FI)
	- Create a model at an appropriate abstraction level (suitable for attacks)

2. MODELING OF RSA EXPONENTIATION EXAMPLE

High-level functional description

- **Inputs**
	- M... plaintext (secret)
	- d… private exponent (secret)
	- n… modulus (public)
- Outputs
	- C… ciphertext (public)
- **·** Implemented functionality
	- $C = M^d \mod n$
- \rightarrow too inaccurate for any meaningful SCA/FI

2. MODELING OF RSA EXPONENTIATION EXAMPLE

In practice

- **RSA** variants
	- Straight-forward variant
	- Chinese Remainder Theorem (CRT)
- Countermeasures in software
	- Exponent blinding: $d_b = d + r_0 * \varphi(n)$
	- Message blinding:
		- $A_0 = 1 + r_1 n \mod r_2 n$
		- $A_1 = M + r_1 n \mod r_2 n$
	- Regular exponentiation (Montgomery Ladder):
		- **•** foreach(db_i in d_b):
			- $A_{\overline{db_i}} = A_0 A_1 \mod n$
			- $A_{db_i} = A_0 A_1 \mod n$
	- Modulus blinding: $w_b = n \times r_3$
	- ..., Exponent splitting, FI countermeasures (redundancy/encoding)
- Countermeasures in hardware
	- e.g., dummy operations, clock jitter, sensors, error counter…
- Do we need to model all this? \rightarrow No \odot

AN EVALUATOR IS NOT AN ATTACKER

■ Remember we are in white-box scenario!

≠

 \blacksquare \rightarrow "Do what only an evaluator can..."

2. MODELING OF RSA EXPONENTIATION EXAMPLE

- Ideally a white box evaluator can...
	- Get special interfaces from developer
	- Access & test subcomponents individually
		- E.g. Montgomery Ladder
	- Control and observer
		- Inputs
		- Countermeasures (enable/disable)
		- Randomness
		- Intermediates
		- Outputs
- In practice ...
	- Not everything can be (directly) controlled/disabled

3. IDENTIFICATION OF SAMPLES

enSSL 0.9.8r 8 Feb 2011 (Library: OpenSSL 0.9.8o 01 Jun 2010)

- Make sure what you are going to test is what shall actually be tested # openssl version
- Different TOEs provided different methods of identification
	- See AGD (guidance) \rightarrow customers need to be provided with a way to ensure they use the correct product and version
- Software TOE
	- Version number return from library function
	- Hashing over SW components
- Hardware TOE
	- Identification plate on chip die
	- or on package

[https://sec-consult.com/en/blog/2019/02/reverse](https://sec-consult.com/en/blog/2019/02/reverse-engineering-architecture-pinout-plc/)[engineering-architecture-pinout-plc/](https://sec-consult.com/en/blog/2019/02/reverse-engineering-architecture-pinout-plc/) \rightarrow Intersting article

4. PREPARATION OF SAMPLES

- Setup according to guidance!?
	- If tests performed on wrong configuration \rightarrow meaningless
- Sample ready to be tested (efficiently)?
	- Collect > 5 Millions of side-channel traces?
	- **Perform multitude of faults?**
- White-box evaluation:
	- Triggers in place? \rightarrow or alternatives?
	- Configuration of countermeasures
	- Chip opened (e.g. access to front or backside)

- Black-box evaluation:
	- Manual deactivation or bypassing of countermeasures
	- Hardware analysis and reverse engineering tasks
		- Decapsulation, thinning, ...

Tools

- **Grinding**
- **Etching**
- **ASAP**
- **Microscope**
- FIB
- **SEM**
- …

- Localization of countermeasures (sensors) and other die features
- Deactivation of countermeasures (FIB)
- Sample preparation for FI
	- Decapsulation (remove package where needed)
	- Thinning of substrate (backside)
	- Polishing of surface

Mostly needed for black-box\grey-box analysis

[Source: https://www.reddit.com/r/Damnthatsinteresting/comments/ci08vx/a_semiconductor_chipic_getting_decapped/](https://www.reddit.com/r/Damnthatsinteresting/comments/ci08vx/a_semiconductor_chipic_getting_decapped/)

Laser decapsulation makes surface too rough for direct use for LFI! \rightarrow Mirror finishing with ASAP (fancy CNC milling machine)

ANALOG SELECTED AREA PREPARATION (ASAP)

- Decapping and/or polishing
	- Goal: thin the substrate from e.g. 925 µm to 50 µm

[Source:](https://www.reddit.com/r/Damnthatsinteresting/comments/ci08vx/a_semiconductor_chipic_getting_decapped/) <https://www.ultratecusa.com/product/asap-1/>

WHY THINNING OF CHIP IS REQUIRED?

Backside IR image w/o thinning of substrate

Backside IR image with thinning of substrate $(50-100 \mu m)$

Whole laser beam absorbed at original substrate thickness of 1mm!**Absorption Depth in Silicon** 1,400 1,300 $\widehat{\mathbf{E}}_{1,100}^{1,200}$ 1064 ni 1,000 depth 900 800 700 Absorption 600 500 400 300 200 532 nm 808 nm 100 550 600 650 700 750 800 850 900 950 1,000 1,050 Wavelength (nm)

He W., Breier J., Bhasin S., Jap D., Ong H.G., Gan C.L. (2016) Comprehensive Laser Sensitivity Profiling and Data Register Bit-Flips for Cryptographic Fault Attacks in 65 Nm FPGA. In: Carlet C., Hasan M., Saraswat V. (eds) Security, Privacy, and Applied Cryptography Engineering. SPACE 2016. Lecture Notes in Computer Science, vol 10076. Springer, Cham. https://doi.org/10.1007/978-3-319-49445-6_3

 \rightarrow Backside LFI will not work w/o thinning because whole energy is absorbed by the substrate

5. ESTABLISHING A COMMUNICATION CHANNEL

Donjon Scaffold Board by Ledger: https://github.com/Ledger-Donjon/scaffold

- Tested devices (e.g. packaged chips) often not designed to be used stand-alone \rightarrow interfaces not very user-friendly
- Or there might exist faster ways to trigger functionality over non-standard interfaces (e.g. debug ports, or dedicated testing interfaces)

Requires either:

- Dedicated hardware
- Versatile hardware (FPGA-based approaches)
- Setting up a communication for a new TOE can take a significant amount of time

6. BYPASSING COUNTERMEASURES

Deactivation of optional countermeasures (guidance)

- ◼ Configuration of accessible countermeasures
	- e.g. use 64 dummy rounds (min. setting) instead of 256 max. available
- White-box evaluation:
	- Control over countermeasures
	- e.g. set randomness to 0 or read random bits
	- Needs to be considered in attack rating
	- \rightarrow not always possible

- Black-box evaluation:
	- **Manual deactivation/bypassing** \rightarrow HW Reverse Engineering

TYPICAL COUNTERMEASURES

Implemented (ideally) on all/various abstraction levels

- **Architectural**
	- Layout\memory scrambling
	- Sensors (rail, light, temperature, etc.)
	- Secure CMOS: WDDL/DPL cells (never perfect, and big)
	- **Obfuscation**
- Logical
	- Secure error messages \rightarrow
- Password is being used by /u/rowealdo37189. Please choose another pass
	- Silent after errors
	- Redundancy, e.g. encrypt/decrypt, encoding/decoding, modular redundancy
	- Error counters
- Algorithm
	- Constant-time algorithms, e.g. Simple Modular Exp. vs Montgommery Ladder
	- Masking /Blinding
	- Hiding: Dummy operations, shuffling, increase noise
- **Physical**
	- Active/passive shielding (using the first metal layers to cover front side)
	- Secure routing (sensitive wires short and packed in between)

[Xuan Thuy](https://dblp.uni-trier.de/pid/136/4513.html) Ngo, [Jean-Luc Danger,](https://dblp.uni-trier.de/pid/52/4689.html) [Sylvain Guilley](https://dblp.uni-trier.de/pid/86/2396.html), [Tarik Graba](https://dblp.uni-trier.de/pid/43/6324.html), [Yves Mathieu,](https://dblp.uni-trier.de/pid/64/1912.html) [Zakaria Najm](https://dblp.uni-trier.de/pid/134/7426.html), [Shivam](https://dblp.uni-trier.de/pid/94/7837.html) Bhasin: **Cryptographically Secure Shield for Security IPs Protection.** [IEEE Trans. Computers](https://dblp.uni-trier.de/db/journals/tc/tc66.html#NgoDGGMNB17) 66(2): 354-360 (2017)

ACTIVE SHIELDING EXAMPLE

- Protects against
	- **Probing from frontside**
	- **LFI from frontside**
	- Circuit manipulation (FIB)
- Usually combined with passive shielding
	- \rightarrow visually block frontside
- Only front-side protection

Chip probing: http://cas.ee.ic.ac.uk/research/photos5.htm

CHIP PROBING EXAMPLE FROM OUR LAB

CIRCUIT MANIPULATION WITH FOCUSED ION BEAM

ZEISS

Gemini 2

http://www.spade.ust.hk/introduction/FIB.html

http://www.ic-crack.com/....

- Uses e.g. Gallium (Ga+) ions + div. gases
- Combined with visualization (SEM)
- **Abilities**
	- Nanometer precision
	- Cut through material (wires/gates)
	- Remove material
	- Add material (rewire, probing points)
- Used for:
	- Deactivating countermeasures (sensors, shields, RNGs)
	- Create probing points
	- Rewire circuit,

NON-INVASIVE BYPASSING OF COUNTERMEASURES I

- Example: Sensors (temperature, light, rail...) combined with error counters
- Fault counter needs to update non-volatile memory (e.g. FLASH) \rightarrow requires higher voltages/energy to write
- React on certain EM/power pattern \rightarrow Rapidly drain voltage supply

(NON-)INVASIVE BYPASSING OF COUNTERMEASURES II

Alternative approach: Find out where not to shoot \odot

- a) Sacrifice some samples (LFI)
- b) Passive imaging technique (OBIC)
- c) Reverse engineering (delayering)

a) LFI Approach

,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,

b) OBIC approach¹

c) Delayering

1) Picture taken from "On the Complexity Reduction of Laser Fault Injection Campaigns Using OBIC Measurements", Schellenberg et al., FDTC 2015: 14-27.

© http://www.ic-crack.com/

7. TARGET IDENTIFICATION

- Spatial / Area of Interest
	- Input from documentation (floor plan)
	- **EXECUTE:** HW reverse engineering
	- Frequency analysis (EM)
	- **Photon Emission Analysis**
- Time / Time of Interest
	- a) Overview trace (SCA)
	- b) I/O signals
	- c) Input/output correlation
	- d) Leakage analysis
	- e) Points of interest selection

LOCALIZATION WITH PHOTON EMISSION ANALYSIS

■ Idea: Stressing transistors emits photons

LOCALIZATION WITH PHOTON EMISSION ANALYSIS

- Idea: Stressing transistors emits photons
- Photons leaking through the substrate can be detected with a very sensitive cooled camera

LOCALIZATION WITH PHOTON EMISSION ANALYSIS

- Idea: Stressing transistors emits photons
- Photons leaking through the substrate can be detected with a very sensitive cooled camera
- **Resulting image:** (IR overlay with PHEMA)

Skorobogatov, S., "Using Optical Emission Analysis for Estimating Contribution to Power Analysis.", FDTC 2009.

8. WORST-CASE ANALYSIS

- Finding a (near) optimal setup for a fault or side-channel analysis is a multidimensional optimization problem
- Example: Laser Fault Injection
	- **Figure 1.5 Front side or back side**
	- **E** Laser source (wavelength, single/multimode, technology)
	- Single or double laser
	- Optical magnification (spot size)
	- **Laser power**
	- **Glitch length**
	- Position (x, y, z)
	- **Timing**
- Argumentation needed why chosen parameter set is the most suitable for attacking

9. ATTACK PATHS AND METHODS

- Lots of ways to attack a function
	- \rightarrow keep scope, testplan, CB recommendations/requirments in mind
- Attack path examples
	- **Cryptanalysis**
	- Side-channel analysis
		- Timing, power, EM, sound, photon emission…
		- Template attacks, Simple power analysis, Differential power analysis
		- \bullet ……
	- **Fault injection**
		- Laser fault injection (LFI), body-bias injection (BBI), EMFI...
		- \bullet ……
- Going into details is beyond this course

9. ATTACK PATHS AND METHODS

A long and winding road...

How to Rate Attacks Example from Common Criteria

CALCULATION OF ATTACK POTENTIAL (SMART CARD)

Each evaluated attack path is subdivided into

- A) Identification \rightarrow how long does it take to find the attack path
- B) Exploitation \rightarrow how long does it take to perform the attack
- Final attack potential $=$ identification $+$ exploitation rating
- Rating depends on:
	- Elapsed time: one hour not practical $(>> 4$ months)
	- Expertise: layman multiple experts
	- Knowledge of TOE : public $-$ not practical
	- Access to TOE: $<$ 10 samples not practical ($>$ 100 samples)
	- Equipment: None multiple bespoke
	- Open samples: public critical (very few open samples/very strong control)

ASSESSMENT OF THE OUTCOME JIL RATING

The evaluator:

- Identified and attack claimed security functionality of a TOE
- The attack was performed within a white box scenario
- The attack was successful, e.g. the evaluator could read out a cryptographic key
- Can this attack be repeated by an attacker in the field?
	- This depends on the potential of the attacker

Table 13: Rating of vulnerabilites and TOE resistance

 $*$ final attack potential = identification + exploitation.

CALCULATION OF ATTACK POTENTIAL (SMART CARD)

- 1 dentification \rightarrow 2+2+0+3+1+2 = 9
- Exploitation \rightarrow 6+4+5+2+4 = 21
- Final attack potential \rightarrow 9 + 21 = 30

- Outcome depends on AVA_VAN level
- Fail?
	- Discussion with developer/sponsor
	- Change guidance (force formerly optional countermeasures)
	- Change TOE
	- Reduce security claim